



END919970013US2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Joseph M. Milewski et al.

Serial No.: 10/001,421

Filed: November 2, 2001

For: LOW TEMPERATURE SOLDER CHIP
ATTACH STRUCTURE (As Amended)

: Art Unit: 2811

: Examiner: Hung K. Vu

: Confirmation No.: 4204

PATENT

2811
#5
Election
5/8/03
afg

RESPONSE TO RESTRICTION REQUIREMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

S I R :

Responsive to the restriction requirement stated in Paper No. 4,
mailed on April 25, 2003, for the application identified above, the Applicants
respond as follows.

The Applicants have been required, under 35 U.S.C. § 121, to elect
for further prosecution the claims of Group I (claims 11-14, which cover an
interconnect structure, classified in class 257, subclass 738) or Group II (claims
15-19, which cover a method of capping a Pb-rich ball, classified in class 438,
subclass 612). The Applicants hereby elect for further prosecution Group I
(claims 11-14). A divisional application may later be filed to prosecute claims
15-19 of Group II. This election is made without traverse.

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The Examiner is invited to call the Applicants' undersigned representative if any further explanation will expedite the prosecution of the application, or if the Examiner has any suggestions or questions concerning the application or the present response.

Respectfully submitted,

RATNERPRESTIA

Daniel N. Calder

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Dated: April 29, 2003

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The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 09-0457 (IBM Corporation) of any fees associated with this communication.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on:

April 29, 2003

Thos M. Cooper